

## Description

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{DS(ON)}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

## Application

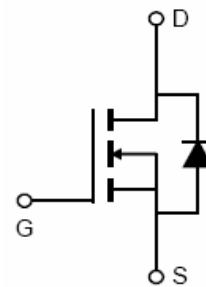
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

## General Features

- $V_{DS} = 85V, I_D = 320A$
- $R_{DS(ON)} = 1.6m\Omega$ , typical @  $V_{GS} = 10V$
- Excellent gate charge x  $R_{DS(on)}$  product(FOM)
- Very low on-resistance  $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating



TO-247



Schematic Diagram

## Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VST08N016-T7	VST08N016	TO-247	-	-	-

## Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	85	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	320	A
Drain Current-Continuous( $T_c=100^\circ C$ )	$I_D (100^\circ C)$	245	A
Pulsed Drain Current	$I_{DM}$	1280	A
Maximum Power Dissipation	$P_D$	365	W
Derating factor		2.43	W/°C
Single pulse avalanche energy <sup>(Note 5)</sup>	$E_{AS}$	2850	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	°C

## Thermal Characteristic

Thermal Resistance, Junction-to-Case	$R_{eJC}$	0.41	°C/W
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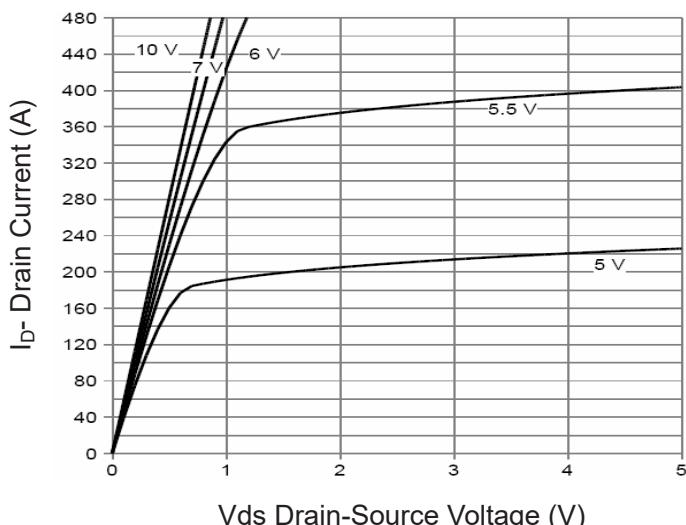
**Electrical Characteristics ( $T_c=25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	85		-	V
Zero Gate Voltage Drain Current	$\text{I}_{\text{DSS}}$	$\text{V}_{\text{DS}}=85\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$\text{I}_{\text{GSS}}$	$\text{V}_{\text{GS}}=\pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	2.0	3.0	4.0	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS(ON)}}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=160\text{A}$	-	1.6	2.0	$\text{m}\Omega$
Forward Transconductance	$\text{g}_{\text{FS}}$	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=160\text{A}$		210	-	S
<b>Dynamic Characteristics</b> (Note 4)						
Input Capacitance	$\text{C}_{\text{iss}}$	$\text{V}_{\text{DS}}=40\text{V}, \text{V}_{\text{GS}}=0\text{V},$ $F=1.0\text{MHz}$	-	15800	-	PF
Output Capacitance	$\text{C}_{\text{oss}}$		-	2450	-	PF
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$		-	111	-	PF
<b>Switching Characteristics</b> (Note 4)						
Turn-on Delay Time	$t_{\text{d(on)}}$	$\text{V}_{\text{DD}}=40\text{V}, \text{I}_D=160\text{A}$ $\text{V}_{\text{GS}}=10\text{V}, \text{R}_G=1.6\Omega$	-	43	-	nS
Turn-on Rise Time	$t_r$		-	39	-	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	108	-	nS
Turn-Off Fall Time	$t_f$		-	40	-	nS
Total Gate Charge	$Q_g$	$\text{V}_{\text{DS}}=40\text{V}, \text{I}_D=160\text{A},$ $\text{V}_{\text{GS}}=10\text{V}$	-	245	-	nC
Gate-Source Charge	$Q_{gs}$		-	66	-	nC
Gate-Drain Charge	$Q_{gd}$		-	65	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	$\text{V}_{\text{SD}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_s=160\text{A}$	-		1.2	V
Diode Forward Current	$\text{I}_s$		-	-	320	A
Reverse Recovery Time	$t_{rr}$	$T_J = 25^\circ\text{C}, I_F = 160\text{A}$ $di/dt = 100\text{A}/\mu\text{s}$ (Note 3)	-	109	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	315	-	nC

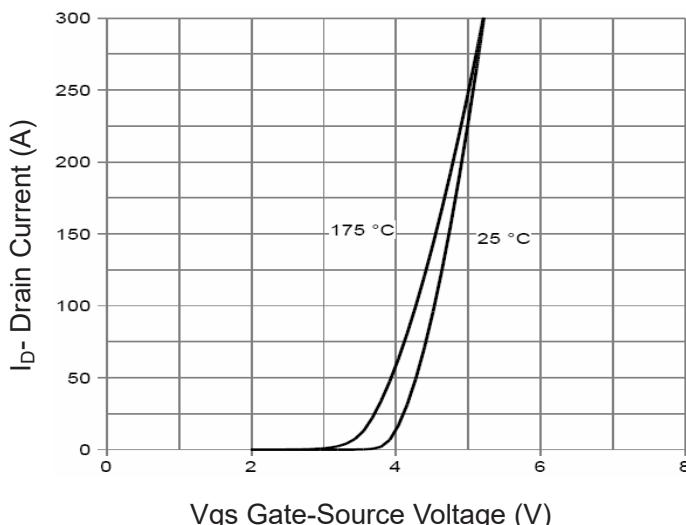
**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5. EAS condition :  $T_J=25^\circ\text{C}, V_{\text{DD}}=40\text{V}, V_G=10\text{V}, L=0.5\text{mH}, R_g=25\Omega$

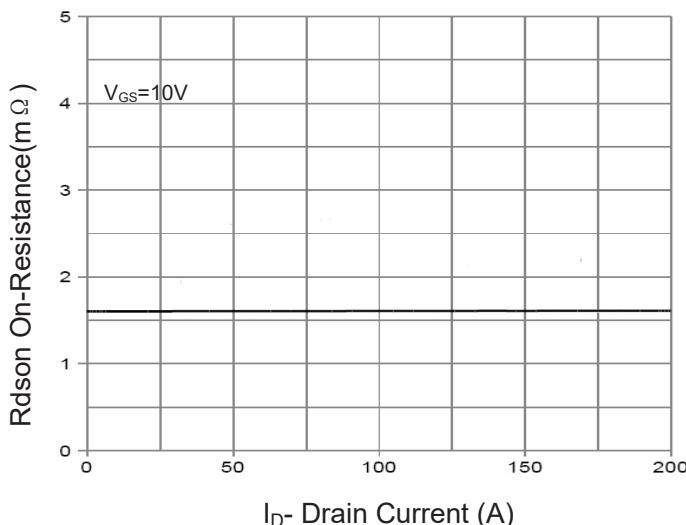
### Typical Electrical and Thermal Characteristics



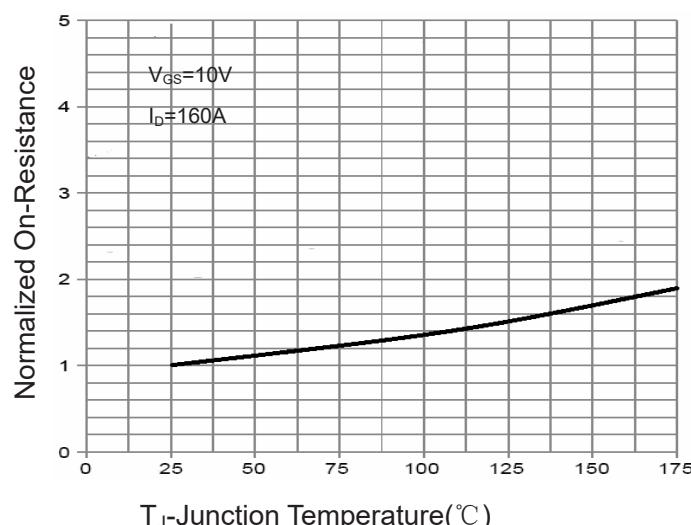
**Figure 1 Output Characteristics**



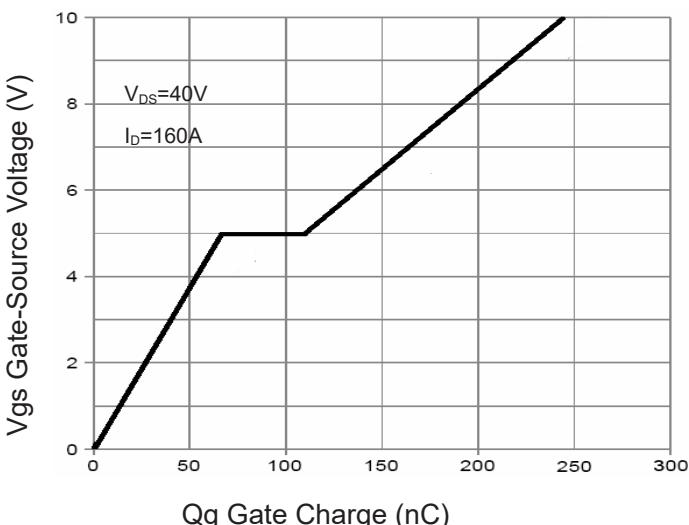
**Figure 2 Transfer Characteristics**



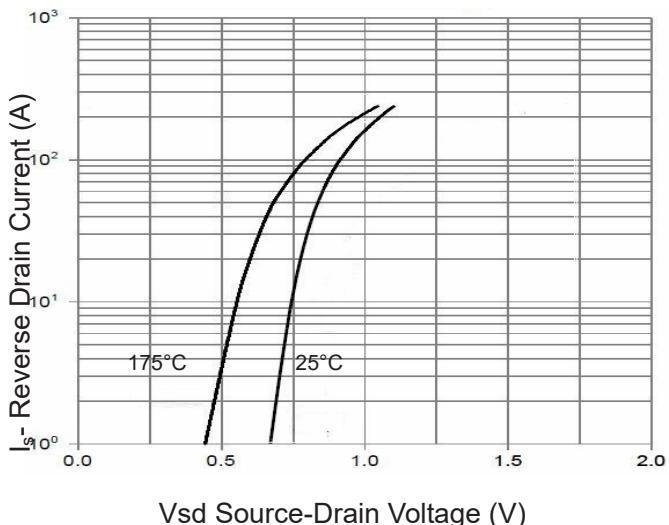
**Figure 3 Rdson- Drain Current**



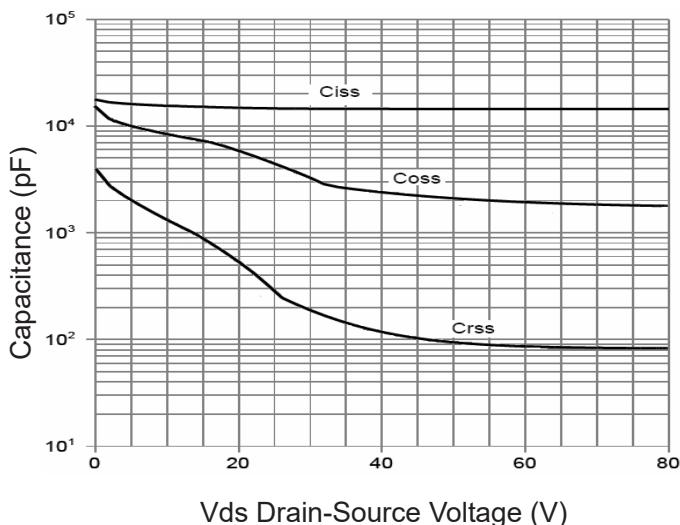
**Figure 4 Rdson-Junction Temperature**



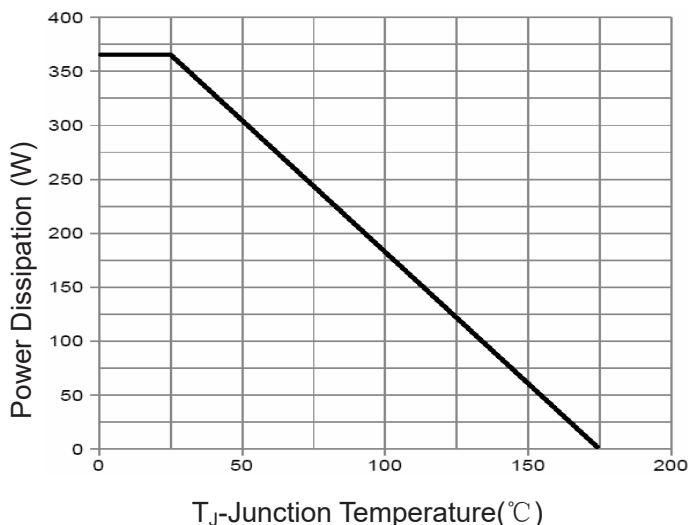
**Figure 5 Gate Charge**



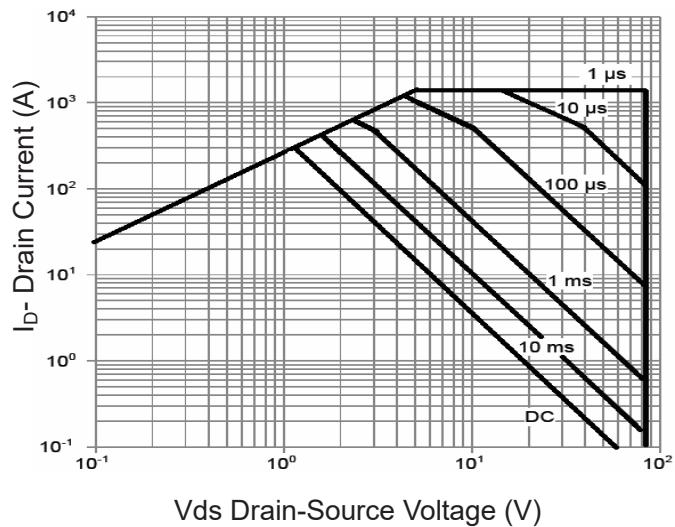
**Figure 6 Source- Drain Diode Forward**



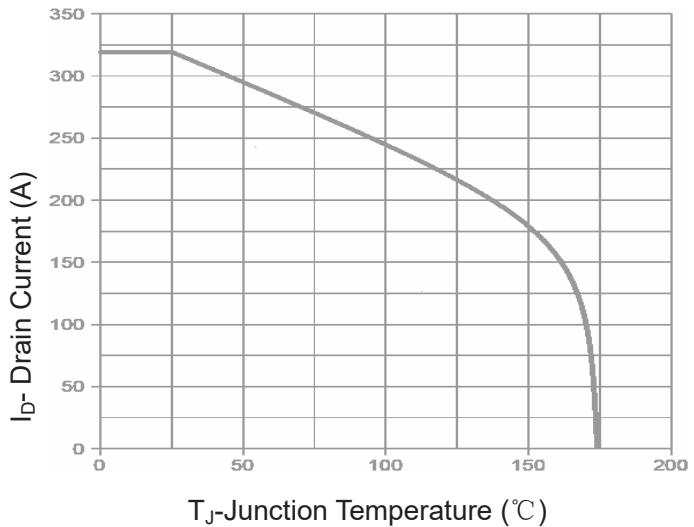
**Figure 7 Capacitance vs Vds**



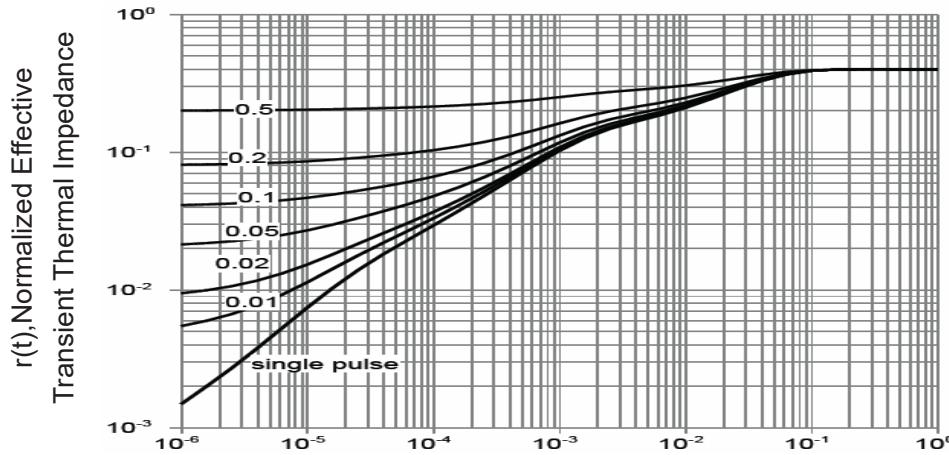
**Figure 9 Power De-rating**



**Figure 8 Safe Operation Area**



**Figure 10 Current De-rating**



**Figure 11 Normalized Maximum Transient Thermal Impedance**